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Re Amended #41  
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BY: Wan Sen DATE: April 3, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor : Barbara Vasquez et al.  
Appl. No. : 10/062,942  
Filed : January 31, 2002  
Title : Method of Applying a Bottom Surface Protective Coating to a Wafer, and Wafer Dicing Method

P R E L I M I N A R Y A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,  
Washington, D. C. 20231

S i r :

Preliminary to examination, kindly amend the above-identified application as follows:

In the Specification:

Please replace the first paragraph on page 1, lines 8-18, with the following paragraph:

21  
The invention lies in the semiconductor processing technology field. More specifically, the present invention relates to a method for applying a protective coating to a bottom surface of a semiconductor wafer or to the bottom surface and all